

**IN THE SPECIFICATION**

Please amend the specification as follows. A marked up version of this amendment is attached as Appendix A.

*For the paragraph bridging between page 1 and page 2 of the specification:*

The multilayer printed wiring board having the filled viahole structure is however disadvantageous in that a surface portion of the plating metal exposed outside the hole for viahole (the surface will be referred to as "viahole surface" henceforth) is easily depressible. If an interlaminar insulative resin layer is formed on a conductor circuitry layer irrespectively of such a depression existent on the viahole surface, a corresponding depression will develop on the surface of the interlaminar insulative resin layer, and cause the plating metal film to break and also a trouble in mounting electronic parts on the wiring board.

**IN THE CLAIMS**

Please cancel claims 4 and 13 without prejudice or disclaimer to file a continuation application.

Please amend claims 1, 9 and 17 as follows. A marked up copy of the amendment is attached as Appendix B.

1. A multilayer printed wiring board comprising conductor circuit layers each having a respective thickness and a surface and interlaminar insulative resin layers